

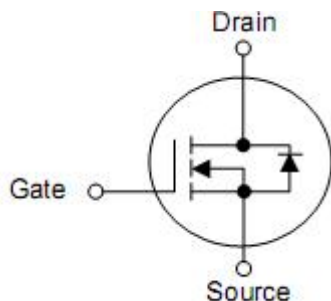
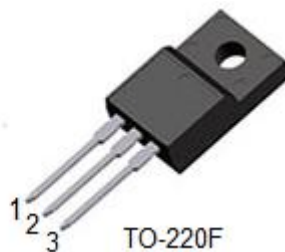
1. Features

- n** $R_{DS(ON)}=3.6\Omega(\text{typ.})@V_{GS}=10V$
- n** Proprietary New Planar Technology
- n** Low Gate Charge Minimize Switching Loss
- n** Fast Recovery Body Diode

2. Applications

- n** CRT,TV/Monitor
- n** Other Applications

3. Symbol



Pin	Function
1	Gate
2	Drain
3	Source

4. Ordering Information

Part Number	Package	Brand
KND4390A	TO-252	KIA
KNF4390A	TO-220F	KIA

5. Absolute maximum ratings

$T_C=25^{\circ}\text{C}$ unless otherwise noted

Parameter		Symbol	Rating		Units
			TO-252	TO-220F	
Drain-source voltage ¹⁾		V_{DSS}	900		V
Gate-to-Source Voltage		V_{GSS}	± 30		V
Continuous drain current	$T_C=25^{\circ}\text{C}$	I_D	4		A
	$T_C=100^{\circ}\text{C}$	I_D	Figure 3		A
Pulsed Drain Current at $V_{GS}=10\text{V}$ ²⁾		I_{DM}	16	Figure 6	A
Single pulse avalanche energy		E_{AS}	650		mJ
Peak Diode Recovery dv/dt ³⁾		dv/dt	5.0		V/ns
Power dissipation	$T_C=25^{\circ}\text{C}$	P_D	90	30	W
	Derate above 25°C		0.72	0.24	W/ $^{\circ}\text{C}$
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10 seconds, Package Body for 10 seconds		T_L T_{PAK}	300 260		$^{\circ}\text{C}$
Operating junction and storage temperature range		T_J, T_{STG}	-55 to 150		$^{\circ}\text{C}$

Caution: Stresses greater than those listed in the “Absolute Maximum Ratings” may cause permanent damage to the device.

6. Thermal characteristics

Parameter	Symbol	Rating		Unit
		TO-252	TO-220F	
Thermal resistance junction-case	$R_{\theta JC}$	1.38	4.17	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	75	100	$^{\circ}\text{C/W}$

7. Electrical characteristics

(T_C=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	900	-	-	V
Drain-source leakage current	I _{DSS}	V _{DS} =900V, V _{GS} =0V	-	-	1	μA
		V _{DS} =720V, T _C =125°C			100	μA
Gate-source forward leakage	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =2.0A	-	3.6	4.8	Ω
Gate threshold voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.0	-	4.0	V
Forward Transconductance ⁴⁾	g _{fs}	V _{DS} =15V, I _D =4.0A	-	5.5	-	S
Input capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V f=1MHz	-	495	-	pF
Reverse transfer capacitance	C _{rss}		-	26	-	pF
Output capacitance	C _{oss}		-	52	-	pF
Total gate charge(10V)	Q _g	V _{DD} =400V, I _D =4A V _{GS} =0~10V	-	15	-	nC
Gate-source charge	Q _{gs}		-	3.1	-	nC
Gate-drain charge	Q _{gd}		-	6.2	-	nC
Turn-on delay time	t _{d(on)}	V _{DD} =400V, V _{GS} =10V, R _G =12Ω, I _D =4A		11		ns
Rise time	t _r			11		ns
Turn-off delay time	t _{d(off)}			32		ns
Fall time	t _f			16		ns
Continuous Source Current ⁴⁾	I _{SD}	Integral PN-diode in MOSFET			4.0	A
Pulsed Source Current ⁴⁾	I _{SM}		-	-	16	A
Diode forward voltage	V _{SD}	I _S =4.0A, V _{GS} =0V,	-	-	1.5	V
Reverse Recovery Time	t _{rr}	V _{GS} =0V, I _F =4.0A, dI _F /dt=100A/μs	-	135	-	nS
Reverse Recovery Charge	Q _{rr}		-	446	-	nC

Note:

1) T_J=+25 °C to +150 °C

2) Repetitive rating; pulse width limited by maximum junction temperature.

3) I_{SD}=4A di/dt<100 A/μs, V_{DD}<BV_{DSS}, T_J=150 °C.

4) Pulse width≤380μs; duty cycle≤2%.

8. Typical operating characteristics

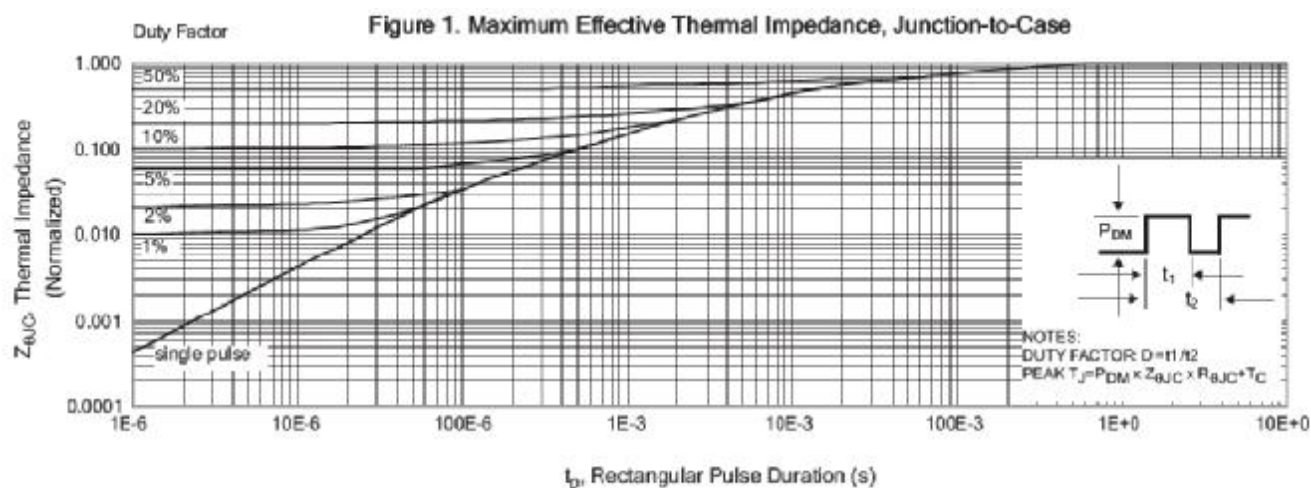


Figure 2.1. Max. Power Dissipation vs Case Temperature (TO-252)

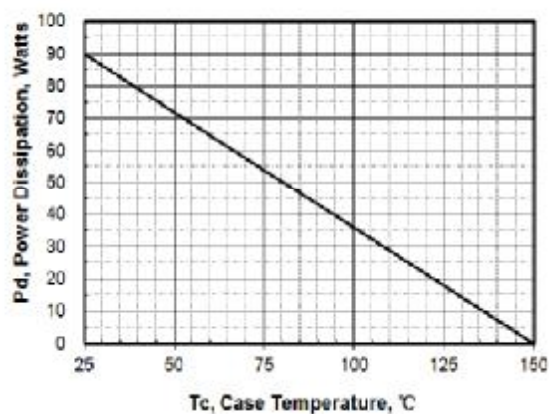


Figure 2.2. Max. Power Dissipation vs Case Temperature (TO-220F)

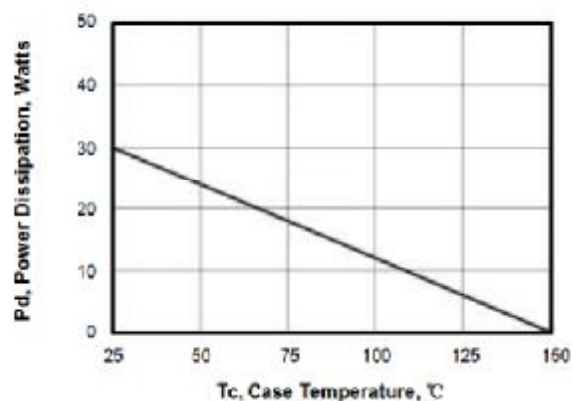


Figure 3. Maximum Continuous Drain Current vs Case Temperature

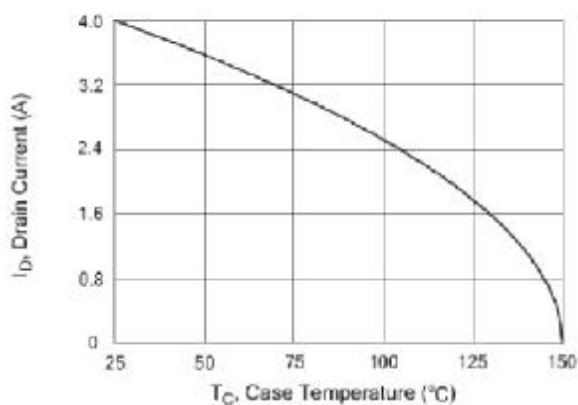


Figure 4. Typical Output Characteristics

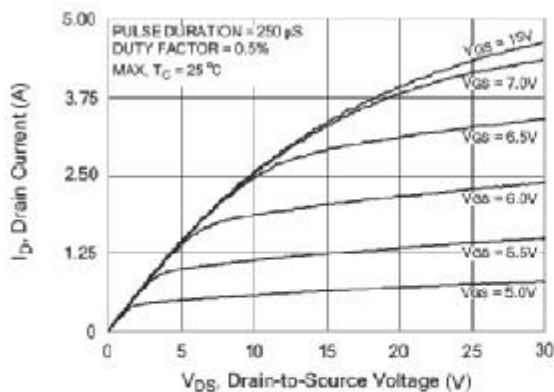


Figure 5. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current

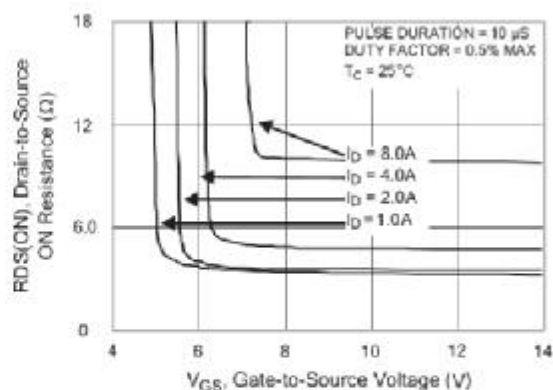


Figure 6. Maximum Peak Current Capability

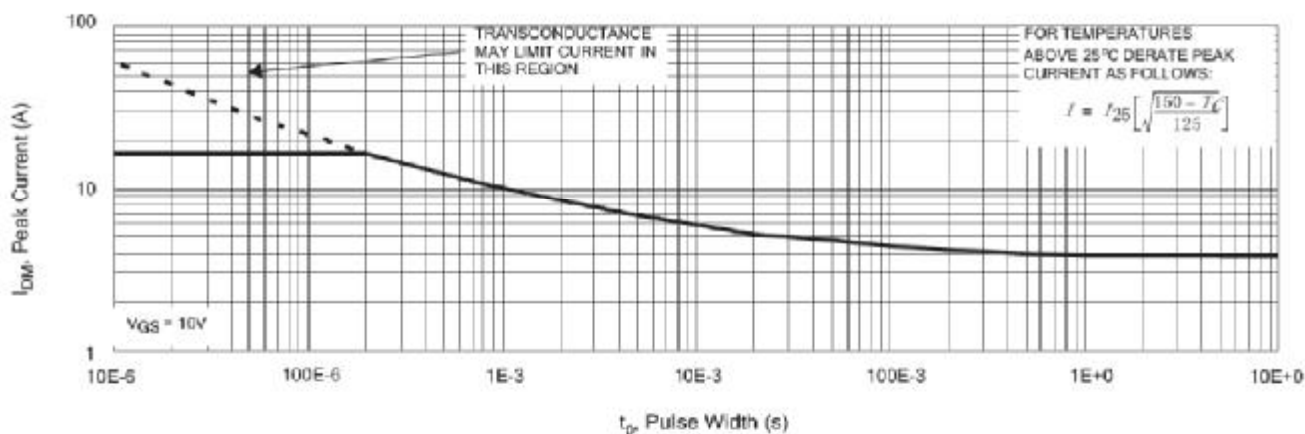


Figure 7. Typical Transfer Characteristics

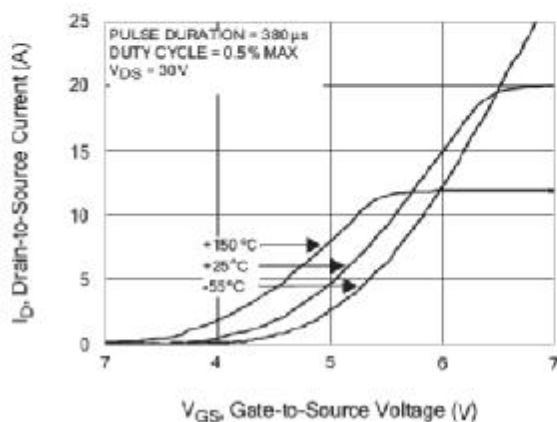


Figure 8. Unclamped Inductive Switching Capability

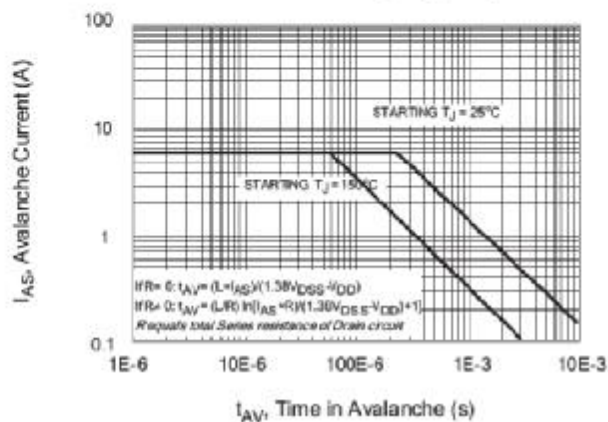


Figure 9. Typical Drain-to-Source ON Resistance vs Drain Current

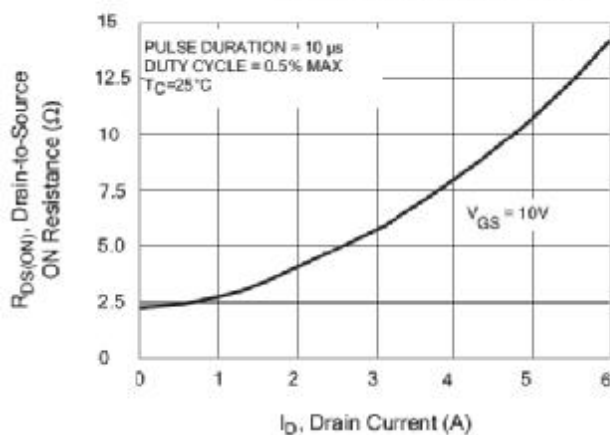


Figure 10. Typical Drain-to-Source ON Resistance vs Junction Temperature

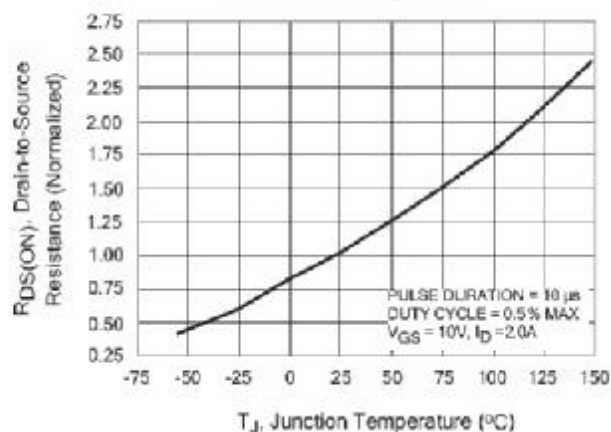


Figure 11. Typical Breakdown Voltage vs Junction Temperature

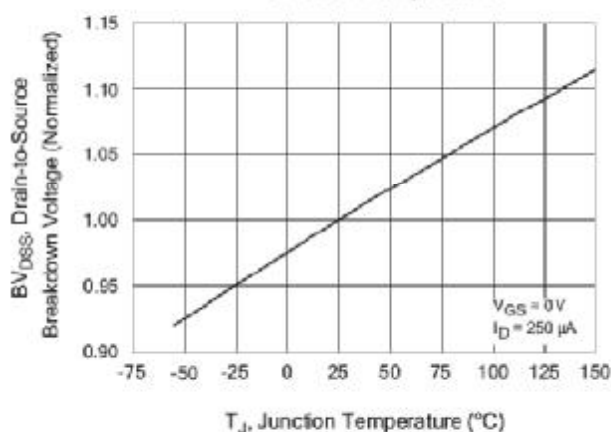


Figure 12. Typical Threshold Voltage vs Junction Temperature

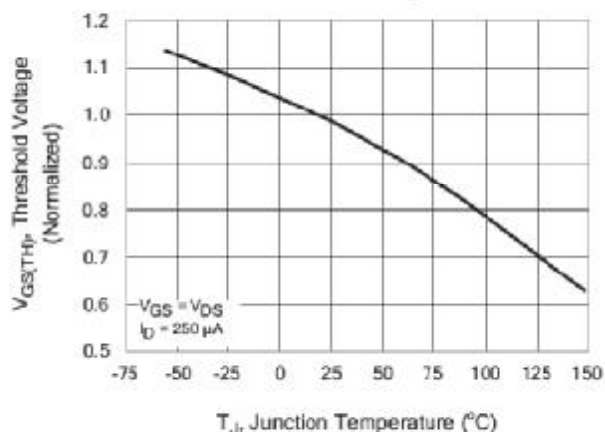


Figure 13. Maximum Safe Operating Area

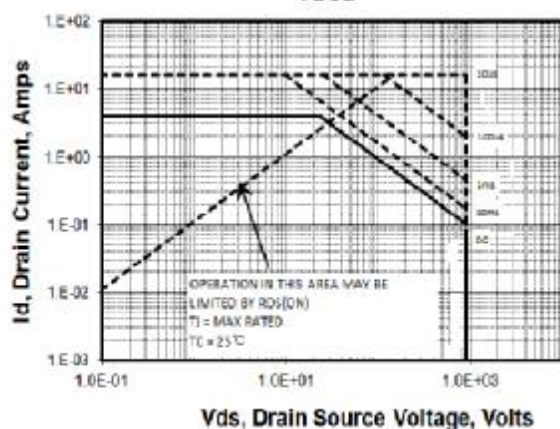


Figure 14. Typical Capacitance vs Drain-to-Source Voltage

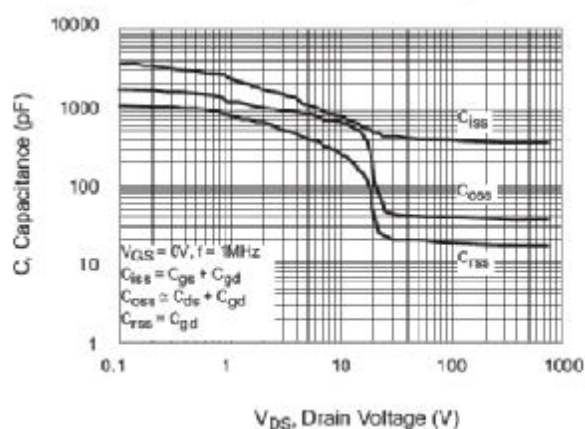


Figure 15. Typical Gate Charge vs Gate-to-Source Voltage

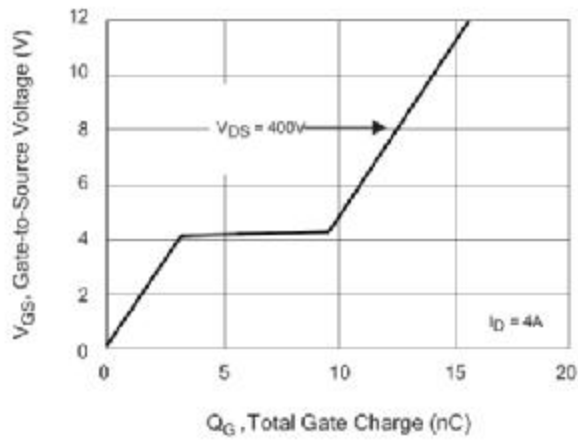
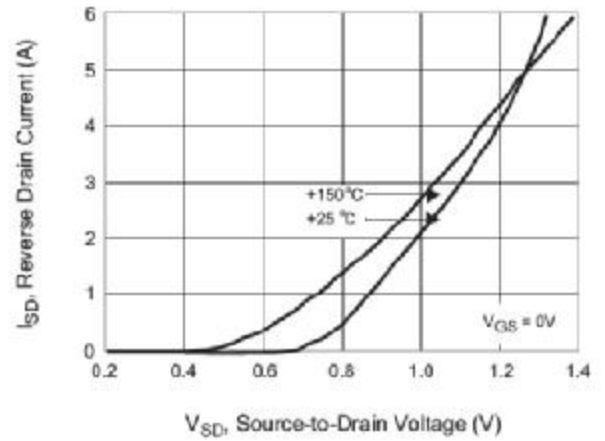


Figure 16. Typical Body Diode Transfer Characteristics



9. Test Circuits and Waveforms

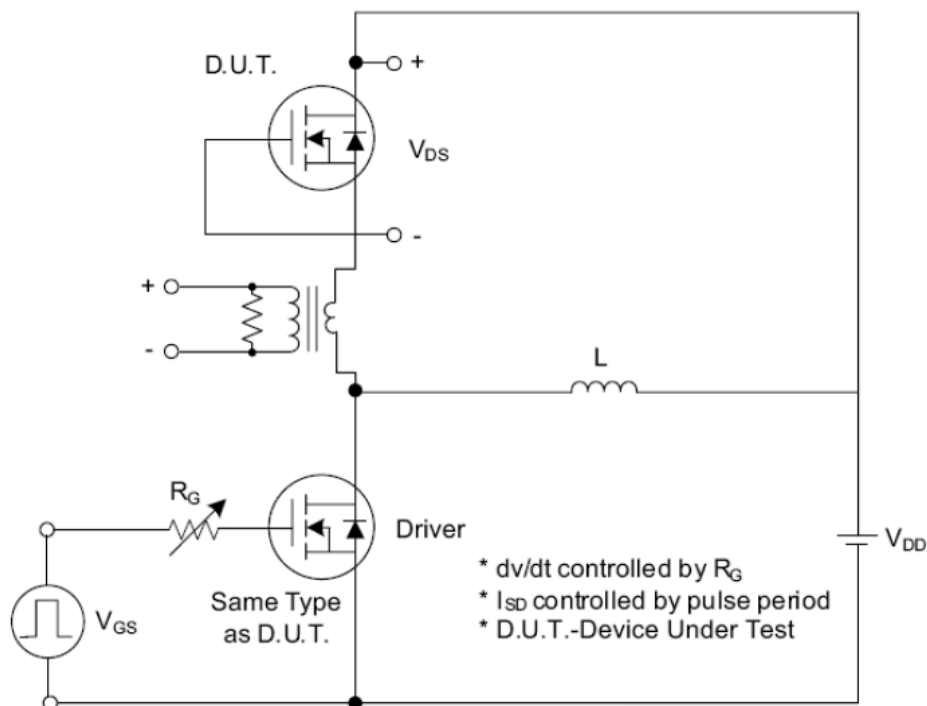


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

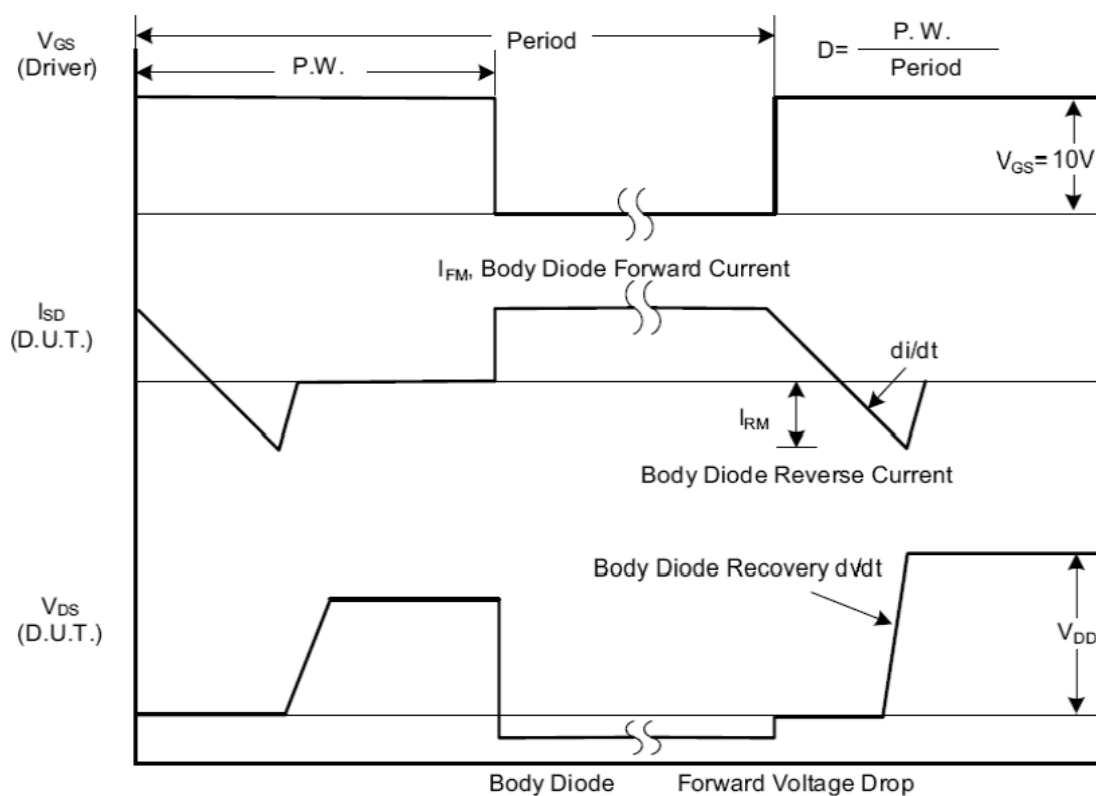


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms

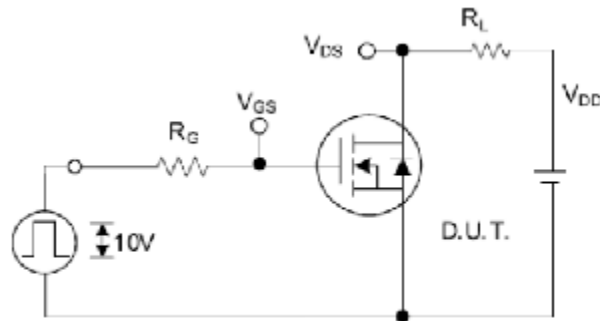


Fig. 2.1 Switching Test Circuit

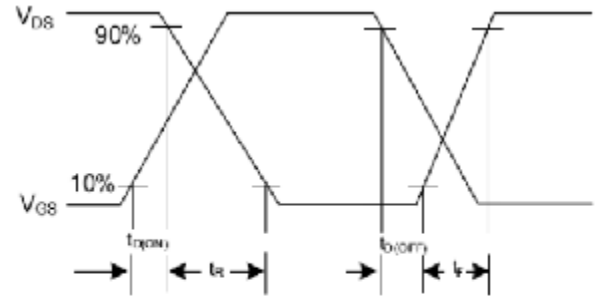


Fig. 2.2 Switching Waveforms

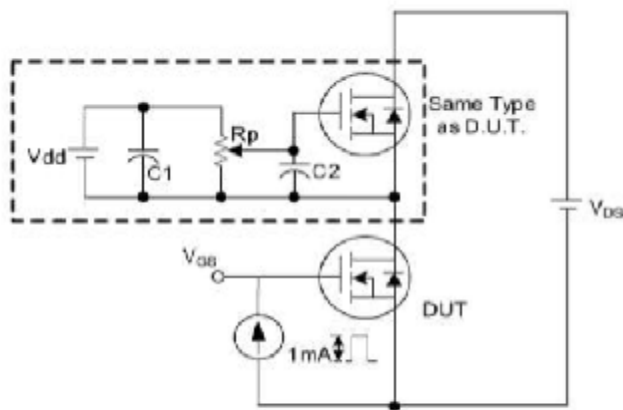


Fig. 3.1 Gate Charge Test Circuit

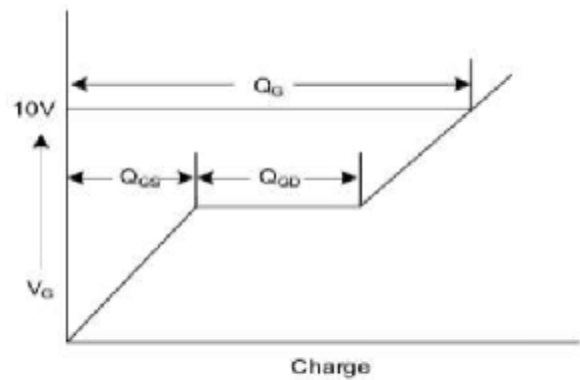


Fig. 3.2 Gate Charge Waveform

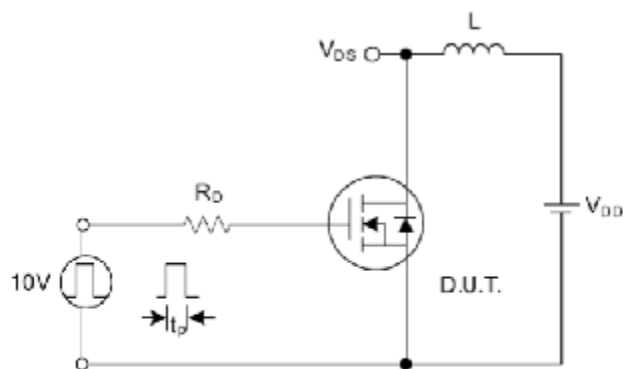


Fig. 4.1 Unclamped Inductive Switching Test Circuit

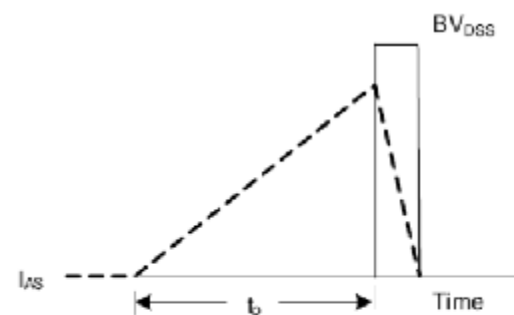


Fig. 4.2 Unclamped Inductive Switching Waveforms